

QL8X12B **pASIC[®] 1 Family** **Very-High-Speed CMOS FPGA**

Rev B

pASIC **HIGHLIGHTS**

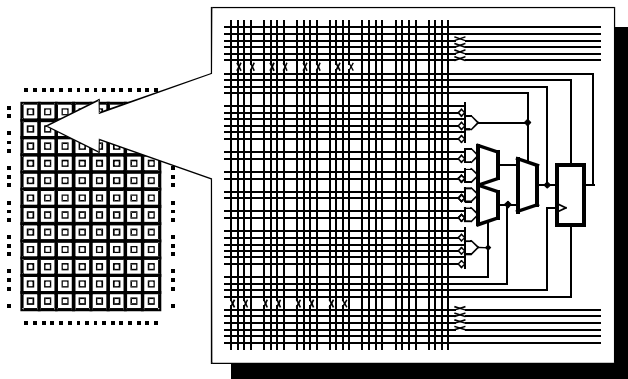
...1,000
usable ASIC gates,
64 I/O pins

QL8x12B
Block Diagram

96 Logic Cells



- ✕ **Very High Speed** – ViaLink[®] metal-to-metal programmable-via antifuse technology, allows counter speeds over 150 MHz and logic cell delays of under 2 ns.
- ✕ **High Usable Density** – An 8-by-12 array of 96 logic cells provides 1,000 usable ASIC gates (2,000 PLD gates) in 44-pin and 68-pin PLCC, and 100-pin TQFP packages.
- ✕ **Low-Power, High-Output Drive** – Standby current typically 2 mA. A 16-bit counter operating at 100 MHz consumes less than 50 mA. Minimum IOL of 12 mA and IOH of 8 mA
- ✕ **Low-Cost, Easy-to-Use Design Tools** – Designs entered and simulated using QuickLogic's new QuickWorks[®] development environment, or with third-party CAE tools including Viewlogic, Synopsys, Mentor, Cadence and Veribest. Fast, fully automatic place and route on PC and workstation platforms using QuickLogic software.



▪ = Up to 56 prog. I/O cells, 6 Input high-drive cells, 2 Input/Clk (high-drive) cells

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pASIC 1

**PRODUCT
SUMMARY**

The QL8x12B is a member of the pASIC 1 Family of very-high-speed CMOS user-programmable ASIC devices. The 96 logic cell field-programmable gate array (FPGA) offers 1,000 usable “gate array” gates (equivalent to 2,000 usable PLD gates) of high-performance general-purpose logic in 44-pin and 68-pin PLCC packages and 100-pin TQFP packages.

Low-impedance, metal-to-metal, ViaLink interconnect technology provides nonvolatile custom logic capable of operating above 150 MHz. Logic cell delays under 2 ns, combined with input delays of under 1.5 ns and output delays under 3 ns, permit high-density programmable devices to be used with today’s fastest microprocessors and DSPs.

Designs can be entered using QuickLogic’s QuickWorks Toolkit or most popular third-party CAE tools. QuickWorks combines Verilog/VHDL design entry and simulation tools with device-specific place & route and programming software. Ample on-chip routing channels allow fast, fully automatic place and route of designs using up to 100% of the logic and I/O cells, while maintaining fixed pin-outs.

FEATURES

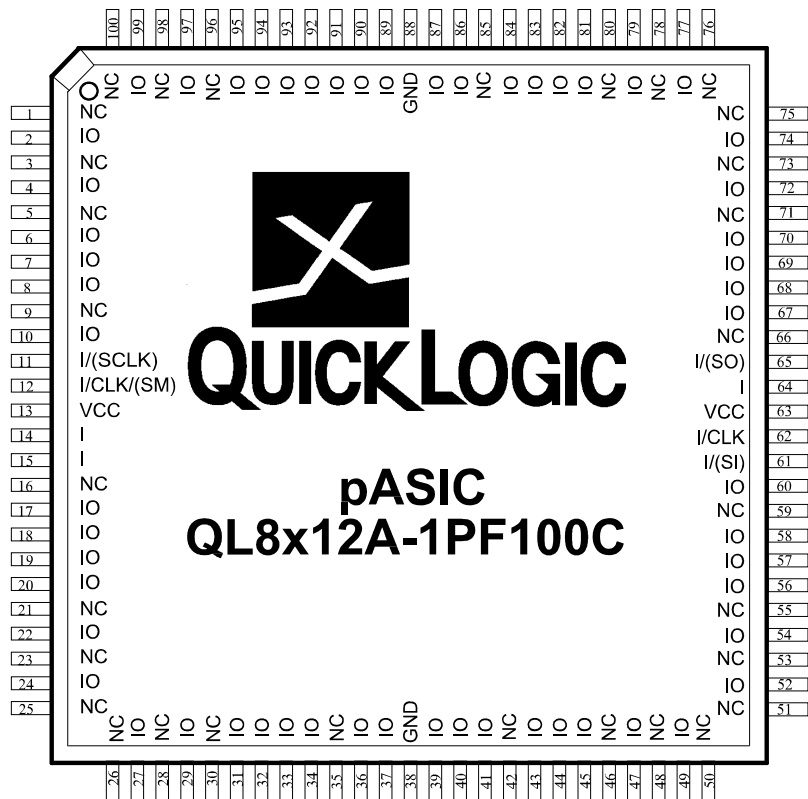
- ✕ Total of 64 I/O pins
 - 56 Bidirectional Input/Output pins
 - 6 Dedicated Input/High-Drive pins
 - 2 Clock/Dedicated input pins with fanout-independent, low-skew clock networks
- ✕ Input + logic cell + output delays under 6 ns
- ✕ Chip-to-chip operating frequencies up to 110 MHz
- ✕ Internal state machine frequencies up to 150 MHz
- ✕ Clock skew < 0.5 ns
- ✕ Input hysteresis provides high noise immunity
- ✕ Built-in scan path permits 100% factory testing of logic and I/O cells and functional testing with Automatic Test Vector Generation (ATVG) software after programming
- ✕ Available packages are 44- and 68-pin PLCC, and a 100-pin TQFP
- ✕ 68-pin PLCC compatible with QL12x16B
- ✕ 100-pin TQFP compatible with QL12x16B and QL16x24B
- ✕ 0.65μ CMOS process with ViaLink programming technology



Pins identified I/SCLK, SM, SO and SI are used during scan path testing operation.



Pinout Diagram 100-pin TQFP





ABSOLUTE MAXIMUM RATINGS

Supply Voltage.....-0.5 to 7.0V
 Input Voltage-0.5 to VCC +0.5V
 ESD Pad Protection..... ±2000V
 DC Input Current ±20 mA
 Latch-up Immunity ±200 mA

Storage Temperature..... -65°C to + 150°C
 Lead Temperature..... 300°C

OPERATING RANGE

Symbol	Parameter	Military		Industrial		Commercial		Unit
		Min	Max	Min	Max	Min	Max	
VCC	Supply Voltage	4.5	5.5	4.5	5.5	4.75	5.25	V
TA	Ambient Temperature	-55		-40	85	0	70	°C
TC	Case Temperature		125					°C
K	Delay Factor	-X Speed Grade		0.4	2.75	0.46	2.55	
		-0 Speed Grade		0.39	1.82	0.46	1.55	
		-1 Speed Grade		0.39	1.56	0.46	1.33	
		-2 Speed Grade			0.4	1.35	0.46	1.25

DC CHARACTERISTICS over operating range

Symbol	Parameter	Conditions	Min	Max	Unit
VIH	Input HIGH Voltage		2.0		V
VIL	Input LOW Voltage			0.8	V
VOH	Output HIGH Voltage	IOH = -4 mA	3.7		V
		IOH = -8 mA	2.4		V
		IOH = -10 µA	VCC-0.1		V
VOL	Output LOW Voltage	IOL = 12 mA*		0.4	V
		IOL = 10 µA		0.1	V
II	Input Leakage Current	VI = VCC or GND	-10	10	µA
IOZ	3-State Output Leakage Current	VI = VCC or GND	-10	10	µA
CI	Input Capacitance [1]			10	pF
IOS	Output Short Circuit Current [2]	VO = GND	-10	-80	mA
		VO = VCC	30	140	mA
ICC	D.C. Supply Current [3]	VI, VIO = VCC or GND		10	mA

*IOL = 12 mA for commercial range only. IOL = 8 mA for the industrial and military ranges.

Notes:

- [1] Capacitance is sample tested only. CI = 20 pF max on I/(SI).
- [2] Only one output at a time. Duration should not exceed 30 seconds.
- [3] Commercial temperature grade only. Maximum Icc for industrial grade is 15mA and for military grade is 20 mA. For AC conditions use the formula described in the Section 9 — Power vs Operating Frequency.
- [4] Stated timing for worst case Propagation Delay over process variation at VCC = 5.0V and TA = 25°C. Multiply by the appropriate Delay Factor, K, for speed grade, voltage and temperature settings as specified in the Operating Range.
- [5] These limits are derived from a representative selection of the slowest paths through the pASIC logic cell **including net delays**. Worst case delay values for specific paths should be determined from timing analysis of your particular design .

**AC CHARACTERISTICS at VCC = 5V, TA = 25°C (K = 1.00)****Logic Cell**

Symbol	Parameter	Propagation Delays (ns)				
		Fanout				
		1	2	3	4	8
tPD	Combinatorial Delay [5]	1.7	2.1	2.6	3.0	4.8
tSU	Setup Time [5]	2.1	2.1	2.1	2.1	2.1
tH	Hold Time	0.0	0.0	0.0	0.0	0.0
tCLK	Clock to Q Delay	1.0	1.5	1.9	2.3	4.2
tCWHI	Clock High Time	2.0	2.0	2.0	2.0	2.0
tCWLO	Clock Low Time	2.0	2.0	2.0	2.0	2.0
tSET	Set Delay	1.7	2.1	2.6	3.0	4.8
tRESET	Reset Delay	1.5	1.8	2.2	2.5	3.9
tSW	Set Width	1.9	1.9	1.9	1.9	1.9
tRW	Reset Width	1.8	1.8	1.8	1.8	1.8

Input Cells

Symbol	Parameter	Propagation Delays (ns) [4]					
		1	2	3	4	6	8
tIN	High Drive Input Delay [6]	2.1	2.2	2.3	2.4	2.6	2.9
tINI	High Drive Input, Inverting Delay [6]	2.1	2.2	2.3	2.5	2.8	3.1
tIO	Input Delay (bidirectional pad)	1.4	1.8	2.2	2.6	3.4	4.2
tGCK	Clock Buffer Delay [7]	2.7	2.7	2.8	2.9	3.0	
tGCKHI	Clock Buffer Min High [7]	2.0	2.0	2.0	2.0	2.0	
tGCKLO	Clock Buffer Min Low [7]	2.0	2.0	2.0	2.0	2.0	

Output Cell

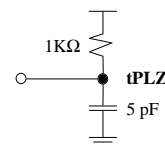
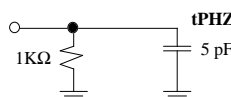
Symbol	Parameter	Propagation Delays (ns) [4]				
		Output Load Capacitance (pF)				
		30	50	75	100	150
tOUTLH	Output Delay Low to High	2.7	3.4	4.2	5.0	6.7
tOUTH	Output Delay High to Low	2.8	3.7	4.7	5.6	7.6
tPZH	Output Delay Tri-state to High	4.0	4.9	6.1	7.3	9.7
tPZL	Output Delay Tri-state to Low	3.6	4.2	5.0	5.8	7.3
tPHZ	Output Delay High to Tri-state [8]	2.9				
tPLZ	Output Delay Low to Tri-state [8]	3.3				

Notes:

[6] See High Drive Buffer Table for more information.

[7] Clock buffer fanout refers to the maximum number of flip flops per half column. The number of half columns used does not affect clock buffer delay.

[8] The following loads are used for tPXZ:





High Drive Buffer

Symbol	Parameter	Clock Drivers Wired Together	Propagation Delays (ns) [4]				
			Fanout				
			12	24	48	72	96
tIN	High Drive Input Delay	1	4.0	4.9			
		2		3.5	5.0		
		3			4.0	4.8	5.6
		4				4.1	4.8
tINI	High Drive Input, Inverting Delay	1	4.2	5.1			
		2		3.7	5.2		
		3			4.2	5.0	5.8
		4				4.3	5.0

AC Performance

Propagation delays depend on routing, fanout, load capacitance, supply voltage, junction temperature, and process variation. The AC Characteristics are a design guide to provide initial timing estimates at nominal conditions. Worst case estimates are obtained when nominal propagation delays are multiplied by the appropriate Delay Factor, K, as specified in the Delay Factor table (Operating Range). The effects of voltage and temperature variation are illustrated in the graphs on page 4-47, K Factor versus Voltage and Temperature. The pASIC Development Tools incorporate data sheet AC Characteristics into the QDIF database for pre-place-and-route timing analysis. The SpDE Delay Modeler extracts specific timing parameters for precise path analysis or simulation results following place and route.

ORDERING INFORMATION

